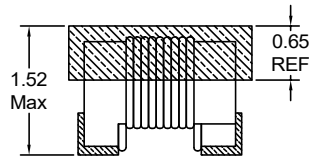


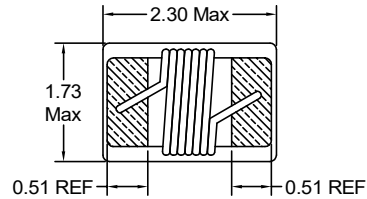
P/N: FAAISC-0805-022J



Outline Dimensions(Unit:mm)

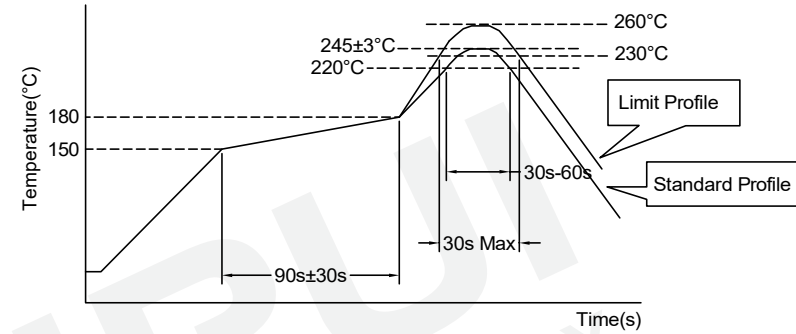


Side view



Bottom view

Recommended Soldering Temperature Graph.



Electrical Schematic



Suggested Pad layout



H	1.78 REF
I	1.02 REF
J	0.76 REF

	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times

Electrical Characteristics(@25°C)

Inductance 250MHz,0.1V	DC Resistance	Rated Current (A Max)	Q Min 500MHz	SRF GHZ Min
22.0nH±5%	220mΩ Max	500mA	55	2.60

General Specifications

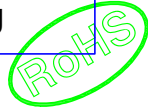
- \*Operating Temperature: -40°C~+125°C (Temperature rise included)
- \*Storage Temperature: -40°C~+125°C
- \*Storage Humidity:RH10%~70%.

Applications

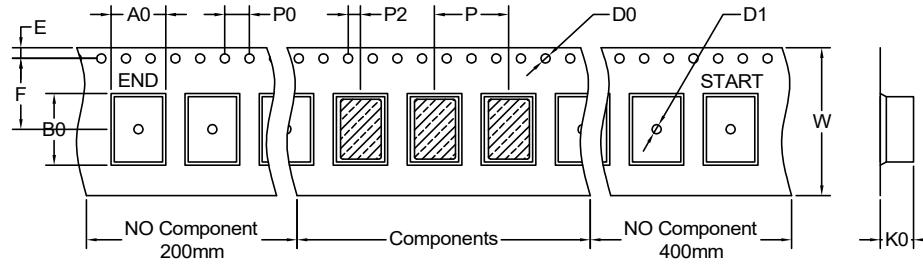
- \*Pagers,Cordless phone
- \*High Freq.Communication Products
- \*GPS(Global Position System)

				Tianchang Fuan Electronic Co Ltd www.fuantronics.net TEL: +86-550-7814888 FAX: +86-550-7831133		 Tolerances unless otherwise specified: (.X)±0.50 (.XX)±0.25 Unit of measurement: mm		Make: Qiumei.Liu Checked: Beson. zhan Approved: Anson. zhan		<b>DRAWING TITLE</b> SURFACE-MOUNT WIRE-WOUND CERAMIC CHIP INDUCTORS		Customer Name: Document/Rev: 2211107/00 Specification Sheet: 1 of 4 Date of Recognition: Nov./03/2022	
REV	DESCRIPTION	APPD	DATE										

P/N: FAAISC-0805-022J



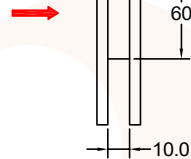
Packing Specifications(Unit:mm):



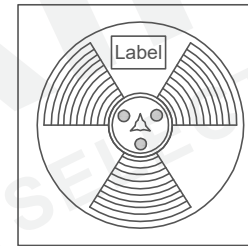
A0	1.30	F	3.50
B0	1.90	D0	1.50
P	2.00	D1	1.50
P0	4.00	K0	1.62
P2	2.00	W	8.00
E	1.75		



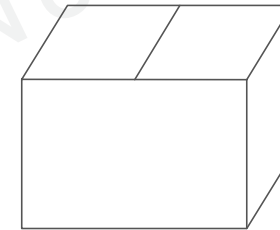
Quantity:2000pcs/Reel



Quantity:2000pcs



Inner box  
Quantity: 20000 pcs/box



Outer cases: 120000pcs/box  
Insufficient boxes filled with inner boxes or fillers

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REV	DESCRIPTION	APPD	DATE					



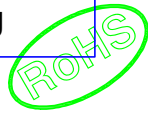
Reliability Testing:

Ltem	Specified value	Test methods
High temperature Storage test Reference documents: MIL-STD-202G Method 108A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $85 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours. Tested not less than 1 hour, not more than 2 hours at room temperature. 
Low temperature Storage test. Referencedocuments: IEC 68-2-1A 6.1 6.2	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $25 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours. Tested not less than 1 hour, not more than 2 hours at room temperature. 
Humidity test Reference Documents: MIL-STD-202G Method 103B	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	1.Dry oven at a temperature of $40^\circ \pm 5^\circ\text{C}$ for 24 hours. 2.Measurements At the end of this period 3.Exposure:Temperature: $40 \pm 2^\circ\text{C}$ ,Humidity: $93 \pm 3\% \text{RH}$ Time: $96 \pm 2$ hours. 4.Tested while the specimens are still in the chamber. 5.Tested not less than 1 hour, nor more than 2 hours at room temperature. 
Heat endurance of Reflow soldering	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Preheat: $150^\circ\text{C}$ ,60 second. Solder:Sn/Ag/Cu. Solder:Temperature: $260 \pm 5^\circ\text{C}$ . Flux:Rosin flux. Reflow peak time 10 second at $260^\circ\text{C}$ 

Ltem	Specified value	Test methods
Thermal shock test Reference documents: MIL-STD-202G Method 107G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ :15 Min 28g $\geq$ weights $\leq 136\text{g}$ :30 Min	First- $40^\circ\text{C}$ for T time,next+ $125^\circ\text{C}$ Ttime as 1 cycle. Go through 20 cycles. 
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	Terminals area must have 95% Min. Solder coverage.	Dip pads in flux then dip in solder pot at $245 \pm 5^\circ\text{C}$ for 5 second. Soler:Sn(93.5)Ag(3.5). Flux:Rosin flux.
Vibration test Reference documents: MIL-STD-202G Method 201A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Apply frequency 10~55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours). 
Drop test Reference documents: MIL-STD-202G Method 203G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ :15 Min 28g $\geq$ weights $\leq 136\text{g}$ :30 Min	Packaged & Drop down from 1m with $981\text{m/s}^2$ (100G)attitude in 1 angle 1 ridges & 2 surfaces orientations.
Terminal strength push test Reference documents: JIS C 5321:1997	Pulling test: DEFINE:A:sectional area of terminal $A \leq 8(\text{Sq M})$ $8(\text{Sq M}) < A \leq 20(\text{Sq M})$ Force $\geq 5\text{N}$ time:30sec $8(\text{Sq M}) < A \leq 20(\text{Sq M})$ Force $\geq 10\text{N}$ time:10sec $20(\text{Sq M}) < A$ force $\geq 20\text{N}$ time:10sec Bending test: Soldering the products on PCB,after the pulling testand bending test, terminal should not pull off	Bend the testing PCB at middle point, the deflection shall be 2mm 

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P/N: FAAISC-0805-022J



Ltem	Specified value	Test methods
Resistance to solvent test Reference documents: IEC 68-2-45:1993	No case deformation or change in appearance, or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min, then drying them at room temp for 5 Min, at last, to brushing making 10 times.
Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
Overload test Reference documents:	1. During the test no smoke, no peculiar, smell, no fire	Apply twice as rated current for 5 minutes.

Recommended solderability temperature profile:



Use rosin-based flux  
Don't use high acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).  
Use lead-free solder, use Sn-3.0Ag-0.5Cu solder  
Standard thickness of solder paste: 0.12-0.15mm

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